



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



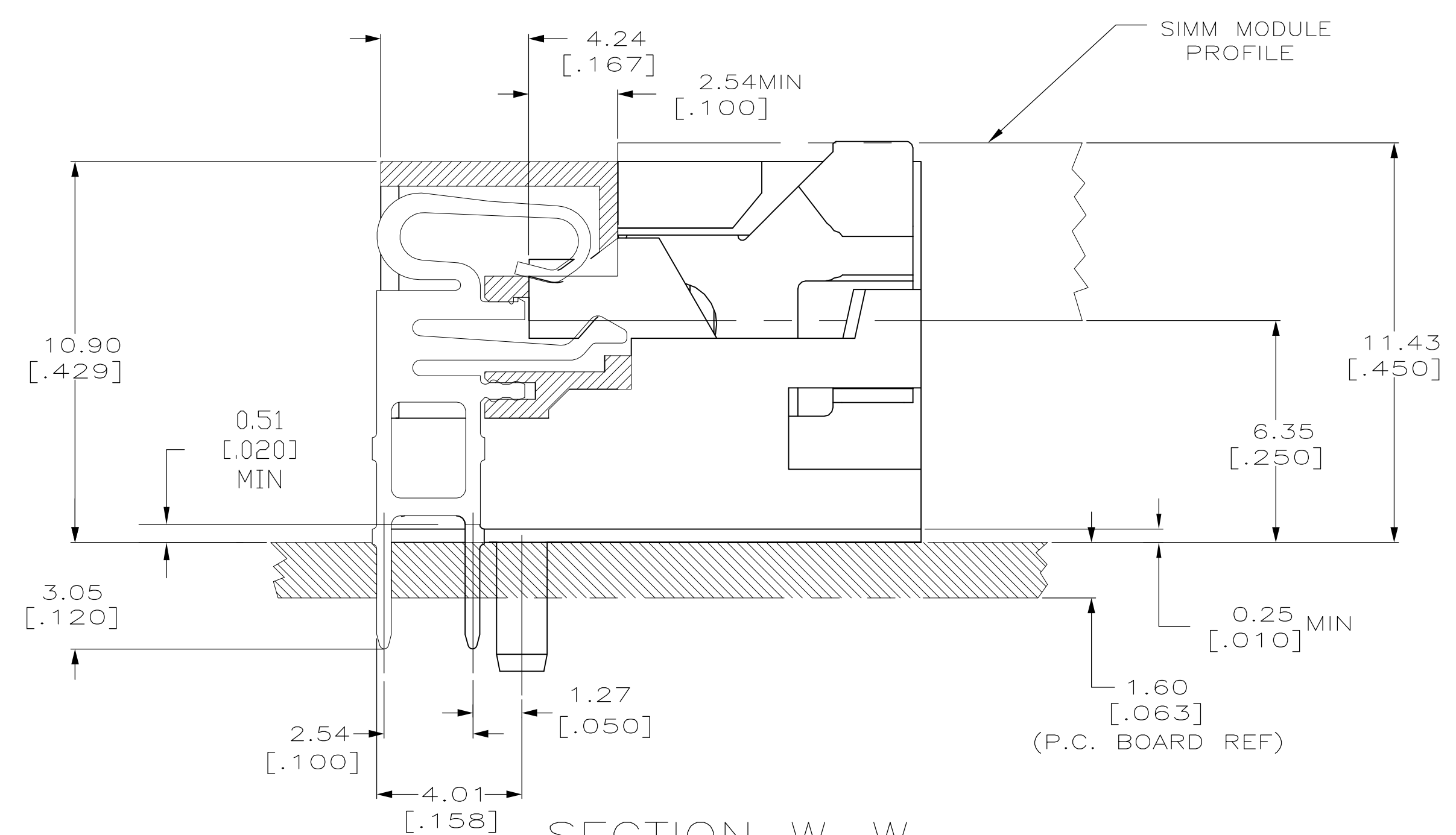
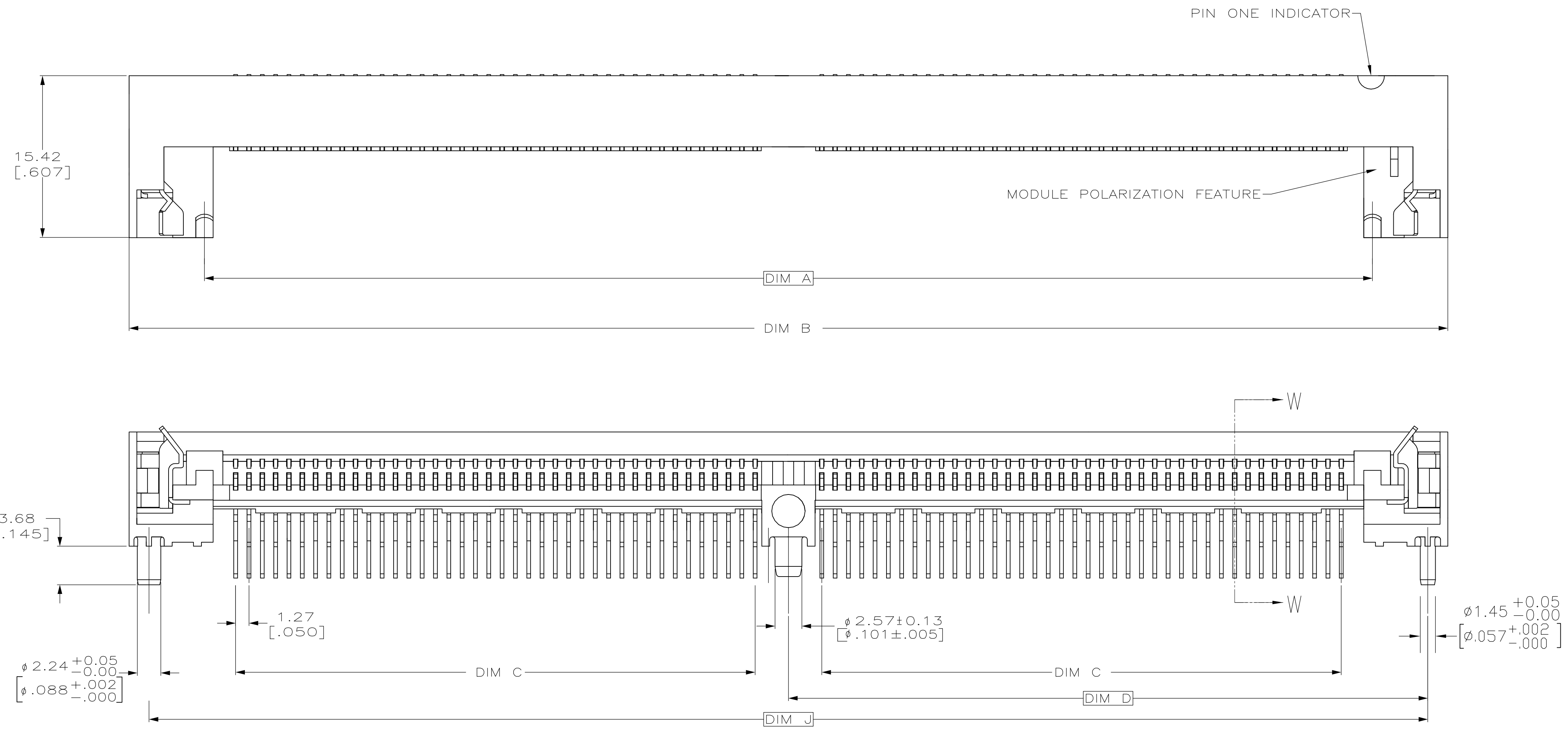
## Contact us

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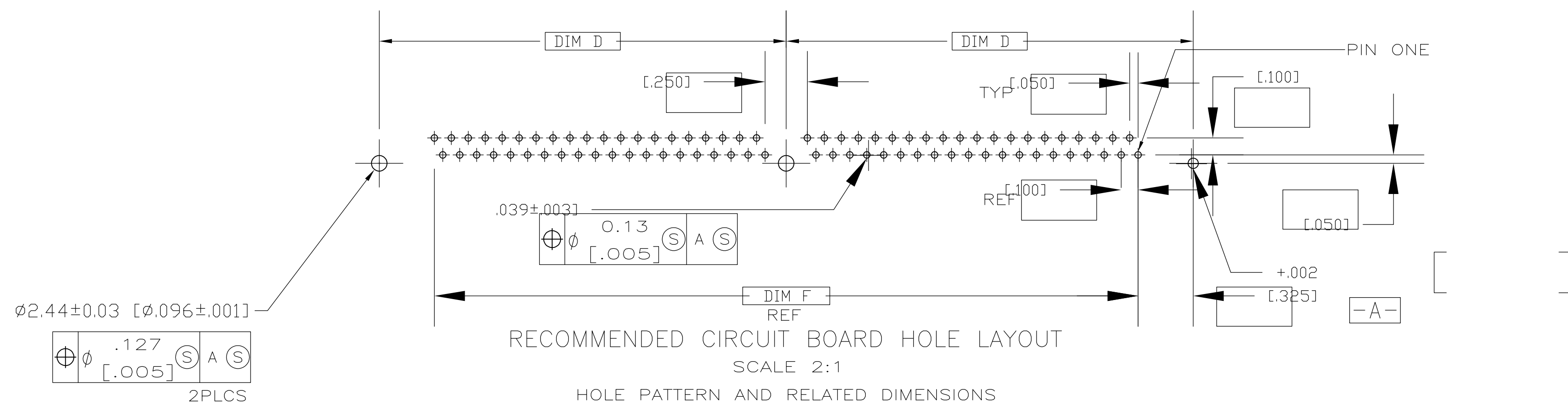
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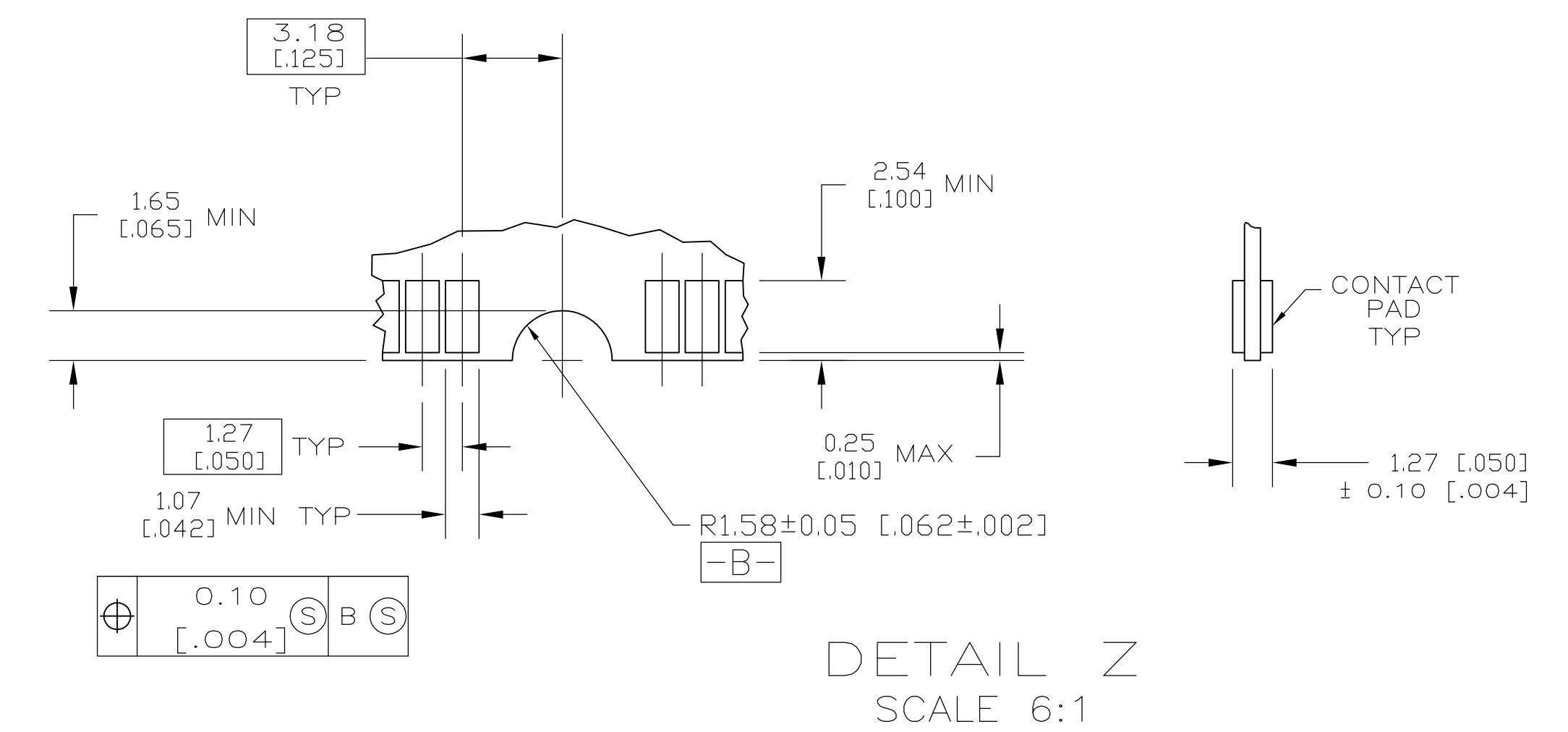
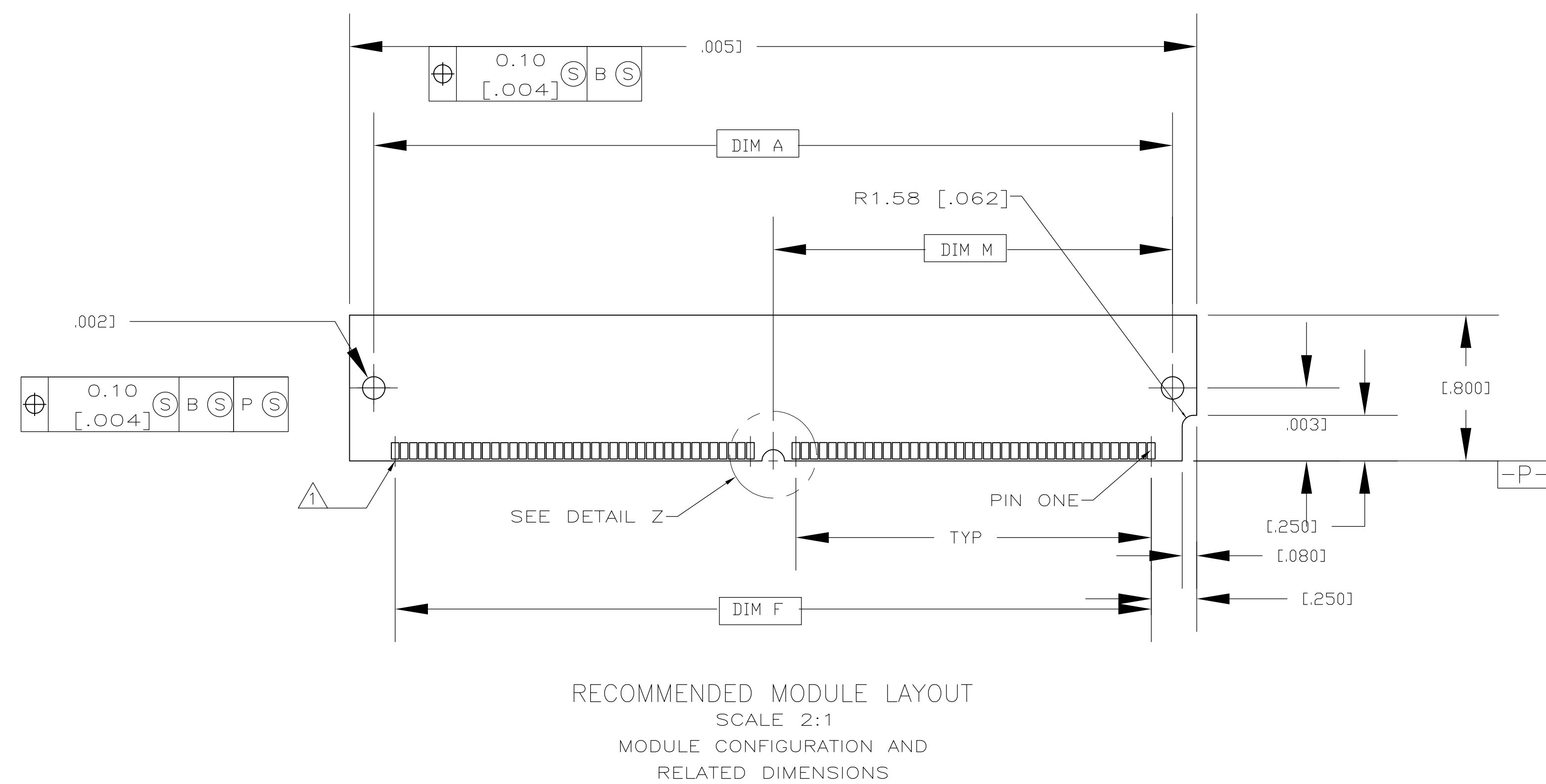


THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN: WENKE HE 29MAR05	 TE Connectivity
DIMENSIONS: mm(INCHES)		CHK: STEVEN YAO 29MAR05	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: TIENOMOTO 29MAR05	
0 PLC ± -	1 PLC ± -	2 PLC ± -	3 PLC ± 0.13(.005)
4 PLC ± -	ANGLES ± -	NAME: SIMM II, RTANG, 1.27 [.050] ASSY, 6.35 [.250] HGT	
MATERIAL: HSG:GLASS REINF LCP (BLACK) CONTACT: PHOS BRONZ	FINISH: 2	PRODUCT SPEC: -	APPLICATION SPEC: -
CUSTOMER DRAWING		SIZE: A1	CAGE CODE: 00779
SCALE: 8:1		DRAWING NO: C=5382487	RESTRICTED TO: -
SHEET 1 OF 2		REV B2	



⚠ FOR OPTIMUM PERFORMANCE, CONTACT PAD PLATING SHOULD BE SMOOTH AND FLAT. COPPER CONTACT PADS ARE TO BE OVERPLATED WITH .00127[.000050] MIN THK NICKEL FOLLOWED WITH .00101[.000040] MIN THK GOLD PLATING.

⚠ CONTACT MATING AREA:  
0.00076 [.000030] MIN THICK GOLD.  
SOLDERTAIL: 0.00005 [.000002] MIN. THK GOLD.  
UNDERPLATE: 0.00127 [.000050] MIN. THK NICKEL OVER ENTIRE CONTACT.



OBSOLETE	58.22 [2.292]	127.00 [5.000]	110.49 [4.350]	123.19 [4.850]	63.50 [2.500]	52.07 [2.050]	130.81 [5.150]	116.43 [4.584]	84	8-5382487-4
	50.60 [1.992]	111.76 [4.400]	95.25 [3.750]	107.95 [4.250]	55.88 [2.200]	44.45 [1.750]	115.57 [4.550]	101.19 [3.984]	72	7-5382487-2
OBSOLETE	48.06 [1.892]	106.68 [4.200]	90.17 [3.550]	102.87 [4.050]	53.34 [2.100]	41.91 [1.650]	110.49 [4.350]	96.11 [3.784]	68	6-5382487-8
Ⓟ	30.28 [1.192]	71.12 [2.800]	54.61 [2.150]	67.31 [2.650]	35.56 [1.400]	24.13 [0.950]	74.93 [2.950]	60.55 [2.384]	40	4-5382487-0
	DIM M	DIM J	DIM F	DIM E	DIM D	DIM C	DIM B	DIM A	POSN	

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm[INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 2 PLC ± - 3 PLC ± 0.13[0.005] 4 PLC ± - ANGLES ± -	DWN: WENKE HE 29MARS CHK: STEVEN YAO 29MARS APVD: T ENOMOTO 29MARS	NAME: SIMM II, RTANG, 1.27 [0.050] ASSY, 6.35 [0.250] HGT
MATERIAL: -	FINISH: -	PRODUCT SPEC: -	APPLICATION SPEC: -
CUSTOMER DRAWING		WEIGHT: -	SIZE: A1
SCALE: 4:1		SHEET: 2 OF 2	REV: B2

STE TE Connectivity